

Manipal Institute of Technology, Manipal

(A Constituent Institute of Manipal University)



III SEMESTER B.TECH (MECHANICAL ENGG.) END SEMESTER (MAKE UP) EXAMINATIONS DEC 2015/JAN 2016

SUBJECT: MANUFACTURING TECHNOLOGY [MME 2105]

REVISED CREDIT SYSTEM

Time: 3 Hours MAX. MARKS: 50

Instructions to Candidates:

- ❖ Answer **ALL** the questions.
- Missing data may be suitable assumed.

1A.	Explain how the grain fineness number of a moulding sand is determined? Also, discuss the various constituents of a moulding sand.	4
1B.	Explain the following special casting techniques with sketches. i) Slush casting ii) Plaster Mould casting	3
1C.	Discuss the working principle of Laser Beam Welding with a sketch. List the merits and demerits of this method.	3
2A.	Explain the following special casting techniques with sketches. i) Cold chamber die casting ii) Centrifugal Casting	4
2B.	Explain the following plastic processing techniques i) Blow Moulding ii) Extrusion Moulding	3
2C.	What is Atomic Hydrogen Arc welding? Explain with a sketch. Also, list the merits and demerits of this welding process.	3
3A.	With help of sketches explain the following sheet metal operations. i) Blanking and Punching, ii) Lancing, iii) Slitting and iv) Notching	4
3B.	With a neat sketch explain the working of electro-chemical machining.	3
3C.	What are the basic characteristics of the electrode materials in electric discharge machining?	3
4A.	Explain with a neat sketch the working of abrasive jet machining.	4
4B.	What are the differences between traditional and non-traditional machining?	3
4C.	With a neat sketch explain the construction and working of radial drilling machine.	3

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- **5A.** With the use of suitable indexing methods find the indexing movement for 99, 26 and 5 divisions for three cylindrical workpieces.
- **5B.** With a neat sketch explain taper turning by tail stock set-over method.
- **5C.** Write a short note on the following bonding materials used in grinding wheels: 3 Vitrified Bond, Silicate Bond and Rubber Bond.

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